

L Number	Hits	Search Text	DB	Time stamp
1	9171	(257/.ccls. and (PCB or (printed adj circuit adj board)))	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/03 09:08
2	2801	((257/.ccls. and (PCB or (printed adj circuit adj board)))) and opening	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/03 09:08
3	3953	((257/.ccls. and (PCB or (printed adj circuit adj board)))) and (opening or cavity)	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/03 10:54
4	505	((257/.ccls. and (PCB or (printed adj circuit adj board)))) and (opening or cavity) and (conduct\$4 adj layers)	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/03 09:20
5	77	((257/.ccls. and (PCB or (printed adj circuit adj board)))) and (isolat\$4 adj layer\$4)	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/03 09:18
6	1614	((257/.ccls. and (PCB or (printed adj circuit adj board)))) and (insulat\$4 adj layer\$4)	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/03 09:18
7	10	((257/.ccls. and (PCB or (printed adj circuit adj board)))) and (isolation adj layer\$s)	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/03 09:18
8	3	((257/.ccls. and (PCB or (printed adj circuit adj board)))) and (isolating adj layer\$s)	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/03 09:18
9	0	((257/.ccls. and (PCB or (printed adj circuit adj board)))) and (isolative adj layer\$s)	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/03 09:19
10	414	((257/.ccls. and (PCB or (printed adj circuit adj board)))) and (insulat\$4 adj layer\$4) and (conduct\$4 adj layers)	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/03 09:20
11	233	((((257/.ccls. and (PCB or (printed adj circuit adj board)))) and (insulat\$4 adj layer\$4)) and (conduct\$4 adj layers)) and (opening or cavity)	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/03 09:20
12	167	(((257/.ccls. and (PCB or (printed adj circuit adj board)))) and (insulat\$4 adj layer\$4)) and (conduct\$4 adj layers)) and (opening or cavity) and wire	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/03 09:31
13	209	(361/778).CCLS.	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/03 10:22
14	106	(361/789).CCLS.	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/03 10:26
15	129	361/795.ccls. and multilayer	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/03 10:29
16	186	361/795.ccls. and component	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/03 10:33

17	14383	257/\$.ccls. and multilayer	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/03 10:34
18	3772	(257/\$.ccls. and multilayer) and (isolate or isolative or isolation or isolating)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/03 10:34
19	2	(257/\$.ccls. and multilayer) and component\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/03 10:35
20	6697	(257/\$.ccls. and multilayer) and component\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/03 10:35
21	3742	((257/\$.ccls. and multilayer) and component\$4) and (bond or bonded or bonding)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/03 10:54
22	884	((257/\$.ccls. and multilayer) and component\$4) and (bond or bonded or bonding)) and (diode or photodiode)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/03 10:36
23	1245	((257/\$.ccls. and multilayer) and component\$4) and (wire adj (bond or bonded or bonding))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/03 10:54
24	579	((257/\$.ccls. and multilayer) and component\$4) and (wire adj (bond or bonded or bonding))) and (opening or cavity)	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/03 10:55